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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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HD74HC679

12-bit Address Comparator

ADE-205-526 (Z)
1st. Edition
Sep. 2000

Description

The HD74HC679 address comparator simplifies addressing of memory boards and/or other peripheral devices. The four P inputs are normally hard wired with a preprogrammed address. An internal decoder determines what input information applied to the 12 A inputs must be low or high to cause a low state at the output (Y). For example, a positive-logic bit combination of 0111 (decimal 7) at the P input determines that inputs A_1 through A_7 must be low and that inputs A_8 through A_{12} must be high to cause the output to go low. Equality of the address amplified at the A inputs to the preprogrammed address is indicated by the output being low.

The HD74HC679 features and enable input ($\overline{G}$). When $\overline{G}$ is low, the device is enabled. When $\overline{G}$ is high, the device is disabled and the output is high regardless of the A and P inputs.

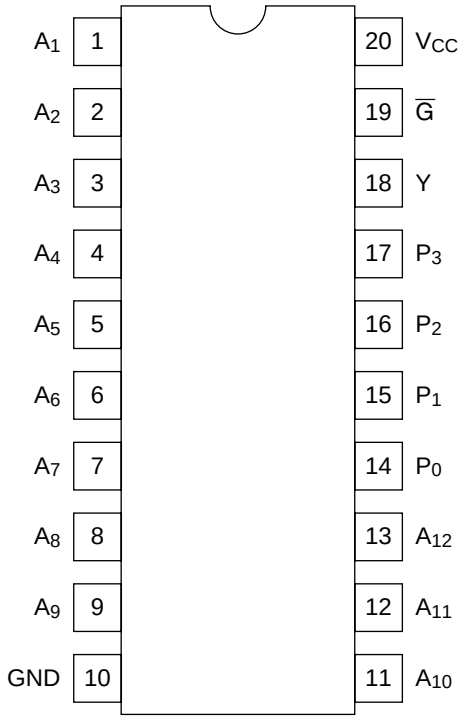
Features

- High Speed Operation: t_{pd} (A to Y) = 18 ns typ (C_L = 50 pF)
- High Output Current: Fanout of 10 LSTTL Loads
- Wide Operating Voltage: V_{CC} = 2 to 6 V
- Low Input Current: 1 μA max
- Low Quiescent Supply Current: I_{CC} (static) = 4 μA max (Ta = 25°C)

Function Table

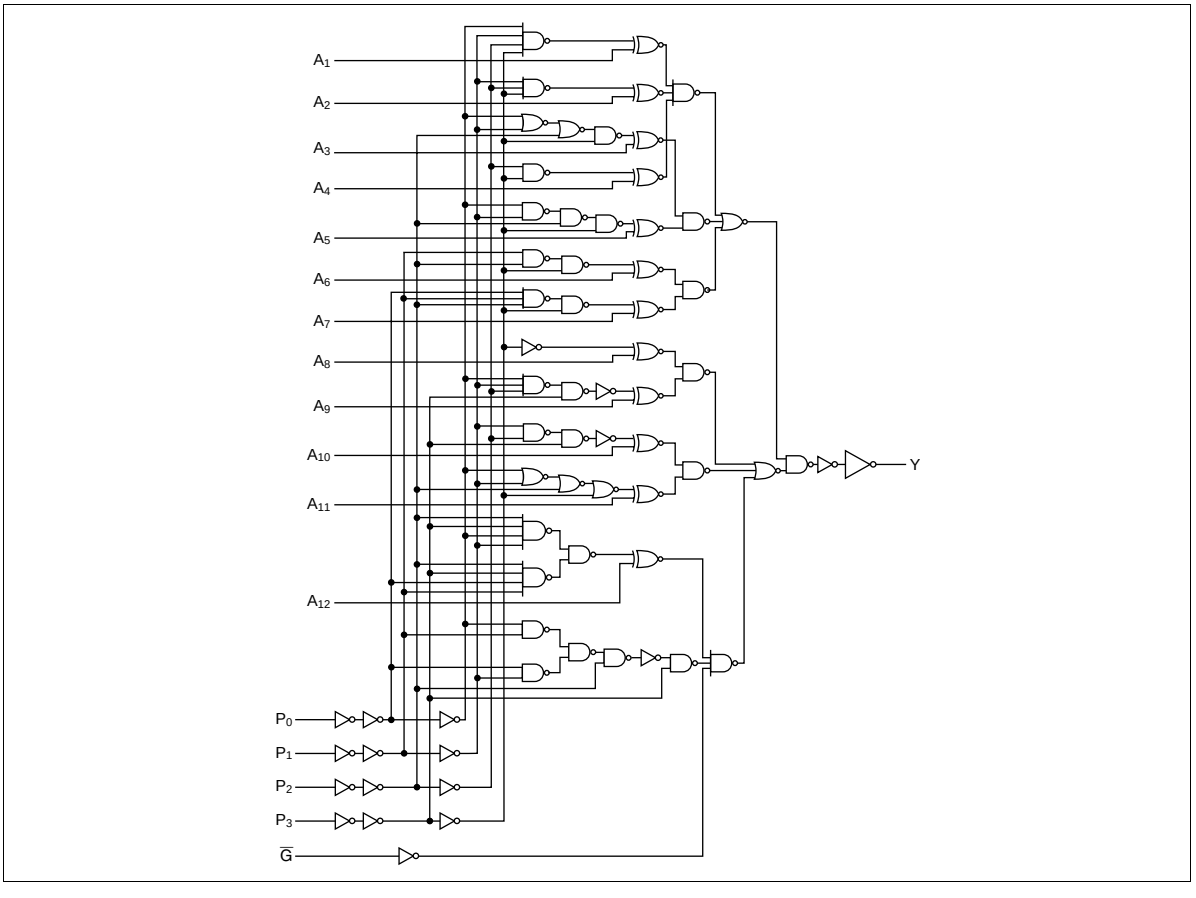
	Inputs																
$\overline{G}$	P_3	P_2	P_1	P_0	A_1	A_2	A_3	A_4	A_5	A_6	A_7	A_8	A_9	A_{10}	A_{11}	A_{12}	Output Y
L	L	L	L	L	H	H	H	H	H	H	H	H	H	H	H	H	L
L	L	L	L	H	L	H	H	H	H	H	H	H	H	H	H	H	L
L	L	L	H	L	L	L	H	H	H	H	H	H	H	H	H	H	L
L	L	L	H	H	L	L	L	H	H	H	H	H	H	H	H	H	L
L	L	H	L	L	L	L	L	L	H	H	H	H	H	H	H	H	L
L	L	H	L	H	L	L	L	L	L	H	H	H	H	H	H	H	L
L	L	H	H	L	L	L	L	L	L	L	H	H	H	H	H	H	L
L	L	H	H	H	L	L	L	L	L	L	L	H	H	H	H	H	L
L	H	L	L	L	L	L	L	L	L	L	L	L	H	H	H	H	L
L	H	L	L	H	L	L	L	L	L	L	L	L	L	H	H	H	L
L	H	L	H	L	L	L	L	L	L	L	L	L	L	L	H	H	L
L	H	L	H	H	L	L	L	L	L	L	L	L	L	L	L	H	L
L	H	H	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L
L	H	H	L	H	X	X	X	X	X	X	X	X	X	X	X	X	H
L	H	H	H	L	X	X	X	X	X	X	X	X	X	X	X	X	H
L	H	H	H	H	L	L	L	L	L	L	L	L	L	L	L	L	L
L	All other combinations																H
H	Any combination																H

Pin Arrangement



(Top view)

Logic Diagram



DC Characteristics

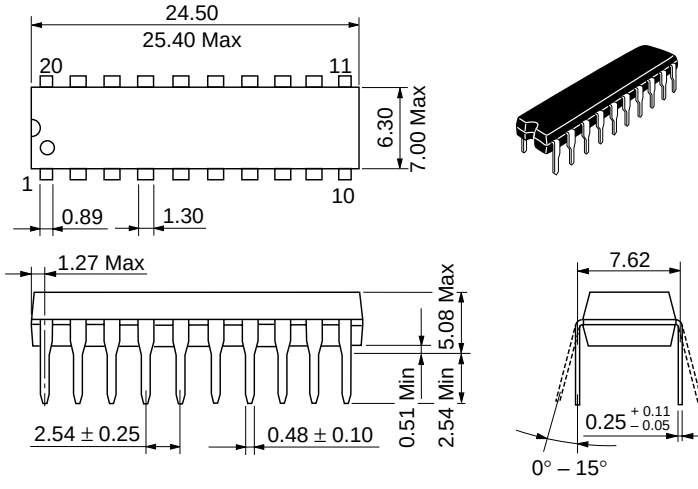
Item	Symbol	V_{CC} (V)	Ta = 25°C Min	Typ	Max	Ta = –40 to +85°C Min	Max	Unit	Test Conditions
Input voltage	V_{IH}	2.0	1.5	—	—	1.5	—	V	
		4.5	3.15	—	—	3.15	—		
		6.0	4.2	—	—	4.2	—		
	V_{IL}	2.0	—	—	0.5	—	0.5	V	
		4.5	—	—	1.35	—	1.35		
		6.0	—	—	1.8	—	1.8		
Output voltage	V_{OH}	2.0	1.9	2.0	—	1.9	—	V	Vin = V_{IH} or V_{IL} I_{OH} = –20 µA
		4.5	4.4	4.5	—	4.4	—		
		6.0	5.9	6.0	—	5.9	—		
		4.5	4.18	—	—	4.13	—		I_{OH} = –4 mA
		6.0	5.68	—	—	5.63	—		I_{OH} = –5.2 mA
	V_{OL}	2.0	—	0.0	0.1	—	0.1	V	Vin = V_{IH} or V_{IL} I_{OL} = 20 µA
		4.5	—	0.0	0.1	—	0.1		
		6.0	—	0.0	0.1	—	0.1		
		4.5	—	—	0.26	—	0.33		I_{OL} = 4 mA
		6.0	—	—	0.26	—	0.33		I_{OL} = 5.2 mA
Input current	Iin	6.0	—	—	±0.1	—	±1.0	µA	Vin = V_{CC} or GND
Quiescent supply current	I_{CC}	6.0	—	—	4.0	—	40	µA	Vin = V_{CC} or GND, Iout = 0 µA

AC Characteristics (C_L = 50 pF, Input $t_r = t_f$ = 6 ns)

Item	Symbol	V_{cc} (V)	Ta = 25°C Min	Typ	Max	Ta = –40 to +85°C Min	Max	Unit	Test Conditions
Propagation delay time	t_{PLH}	2.0	—	—	310	—	390	ns	P to Y
	t_{PHL}	4.5	—	27	62	—	78		
		6.0	—	—	52	—	66		
	t_{PLH}	2.0	—	—	180	—	225	ns	A to Y
	t_{PHL}	4.5	—	18	36	—	45		
		6.0	—	—	31	—	38		
	t_{PLH}	2.0	—	—	125	—	155	ns	$\overline{G}$ to Y
	t_{PHL}	4.5	—	14	25	—	31		
		6.0	—	—	21	—	26		
Output rise/fall time	t_{TLH}	2.0	—	—	75	—	95	ns	
	t_{THL}	4.5	—	5	15	—	19		
		6.0	—	—	13	—	16		
Input capacitance	Cin	—	—	5	10	—	10	pF	

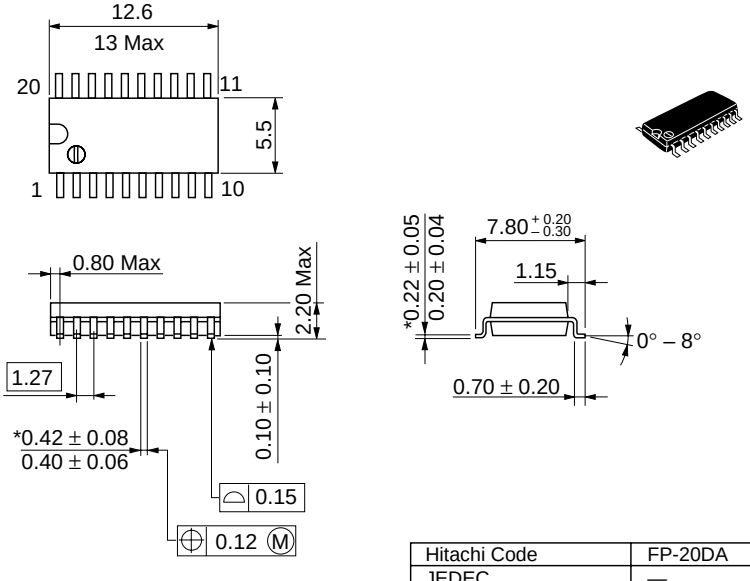
Package Dimensions

Unit: mm



Hitachi Code	DP-20N
JEDEC	—
EIAJ	Conforms
Mass (reference value)	1.26 g

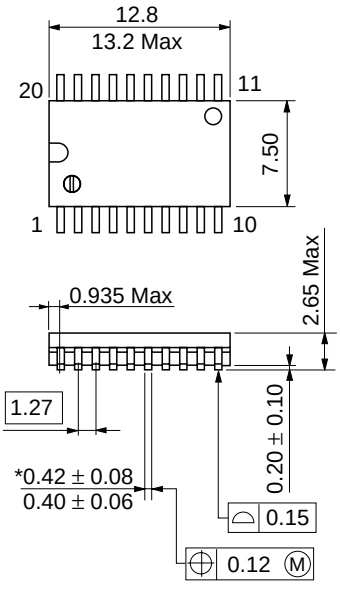
Unit: mm

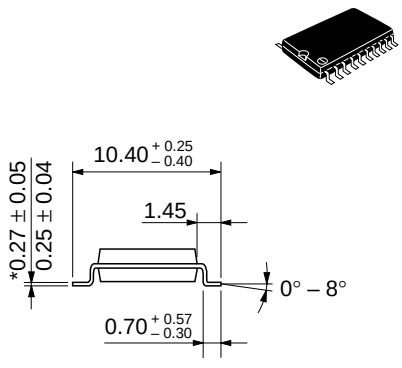


*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-20DA
JEDEC	—
EIAJ	Conforms
Mass (reference value)	0.31 g

Unit: mm





*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-20DB
JEDEC	Conforms
EIAJ	—
Mass (reference value)	0.52 g

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